Chip Magnification 2–32X Semi Automatic BGA Rework Station Suitable for Chip Size 1×1mm – 70×70mm PCB Thickness 0.3–5mm WDS-620 Rework Solution

Our Product Introduction

Basic Information

- Brand Name: Wisdomshow
- Certification: CE
- Model Number: WDS-620
- Minimum Order Quantity: 1
- Packaging Details: Wooden Case
- Delivery Time: 3-5days
- Payment Terms: TT
- Supply Ability: 200Sets / Month



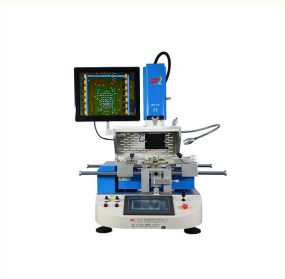
Product Specification

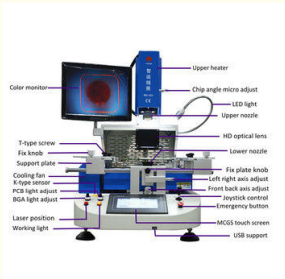
- Thermocouple Ports: 2 Pcs
- Temperature Control: High-precision K-type Thermocouple (Ksensor), Closed Loop Control; Independent Upper & Lower Temperature Control, Accuracy Up To ±1°C
- Max Placement Load: 300g
- Applicable Chip Size: 1×1mm – 70×70mm
- Placement Accuracy: ±0.02mm
- Lower Infrared Heating Power: 2700W (1200W Controlled)
- Min PCB Size: 10×10mm
- Positioning Method: V-shaped Slot + Universal Fixture + Quick Positioning With Laser Alignment Lamp



More Images









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Product Description

Product Description:

WDS-620 Semi-Automatic BGA Rework Station

WDS-620 is a professional semi-automatic BGA rework station, specially developed for soldering and desoldering BGA, QFN, CSP and other fine-pitch IC chips on PCBs. It is widely used for motherboard repair, electronics maintenance and small-batch PCB rework.

Core Advantages

Closed-loop K-type thermocouple temperature control, upper and lower heating zones controlled separately, temperature accuracy ±1°C, stable heating and avoid chip damage.

Laser positioning lamp + V-shaped slot + universal fixture, fast and convenient chip alignment.

HD optical vision system with 2~32X magnification, clear observation for tiny chips.

High placement accuracy ±0.02mm, max placement load up to 300g, stable for precise chip mounting.

Compatible with a wide range of PCB and chip sizes: PCB 10×10mm ~ 480×380mm, applicable chips 1×1mm ~70×70mm, minimum chip pitch 0.15mm.

Application

Perfect for electronics repair workshops, mobile mainboard repair, lab maintenance, semiconductor and PCB rework jobs.

Basic Parameters

Total Power: 5200W

Power Supply: AC 220V±10%, 50/60Hz

Dimension: L705×W655×H710mm

Net Weight: 55kg

PCB Thickness: 0.3–5mm

Technical Parameters:

Electrical Components	High-sensitivity Touch Screen + Self-developed MCU + Stepper Motor
Max Placement Load	300g
Applicable Chip Size	1×1mm – 70×70mm
Dimensions	L705×W655×H710mm
Placement Accuracy	±0.02mm
Temperature Control	High-precision K-type Thermocouple (K sensor), Closed Loop Control; Independent Upper & Lower Temperature Control, Accuracy Up To ±1°C
Min PCB Size	10×10mm
Upper Heating Power	1200W
Lower Heating Power	1200W
Net Weight	55kg

Applications:

The Wisdomshow WDS-620 Semi Automatic BGA Rework Station is a highly efficient and reliable solution designed for precision soldering and repair of BGA (Ball Grid Array) components. Originating from Shenzhen, China, and certified with CE standards, this

advanced rework station is ideal for electronics manufacturers, repair shops, and R&D laboratories requiring precision and consistency in their rework processes. With a minimum order quantity of just one unit and a supply ability of 200 sets per month, Wisdomshow ensures timely delivery within 3-5 days, neatly packaged in a sturdy wooden case to guarantee safe transit.

This Semi Automatic BGA Rework Station features a powerful lower heating power of 1200W and a unique three heating zone design, enabling uniform and controlled temperature distribution. This is critical for preventing thermal damage to sensitive electronic components during the rework process. The station's precision is further enhanced by its innovative positioning method, which combines a V-shaped slot, universal fixture, and quick positioning facilitated by a laser alignment lamp. This ensures perfect alignment of BGA chips, reducing errors and improving repair success rates.

Equipped with a high-sensitivity touch screen, self-developed MCU, and stepper motor, the WDS-620 offers intuitive control and stable operation. The chip magnification ranges from 2 to 32 times, allowing technicians to inspect and manipulate tiny components with ease. Suitable for handling components with a maximum placement load of up to 300 grams, this BGA rework station is versatile enough for a wide range of electronic devices, from smartphones and tablets to industrial circuit boards.

Typical application scenarios for the Wisdomshow WDS-620 include repairing defective BGA chips on motherboards, upgrading firmware chips, and replacing damaged ICs in consumer electronics, automotive electronics, telecommunications equipment, and aerospace components. Its semi automatic functionality streamlines the rework process, saving time and reducing manual errors, making it an essential tool for technicians and engineers involved in PCB assembly and repair.

In summary, the Wisdomshow WDS-620 Semi Automatic BGA Rework Station is a robust, precise, and user-friendly device designed to meet the demanding needs of modern electronics manufacturing and repair. Its combination of three heating zone technology, advanced positioning methods, and intelligent control systems makes it a standout choice for anyone looking to perform reliable BGA rework efficiently and accurately.

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